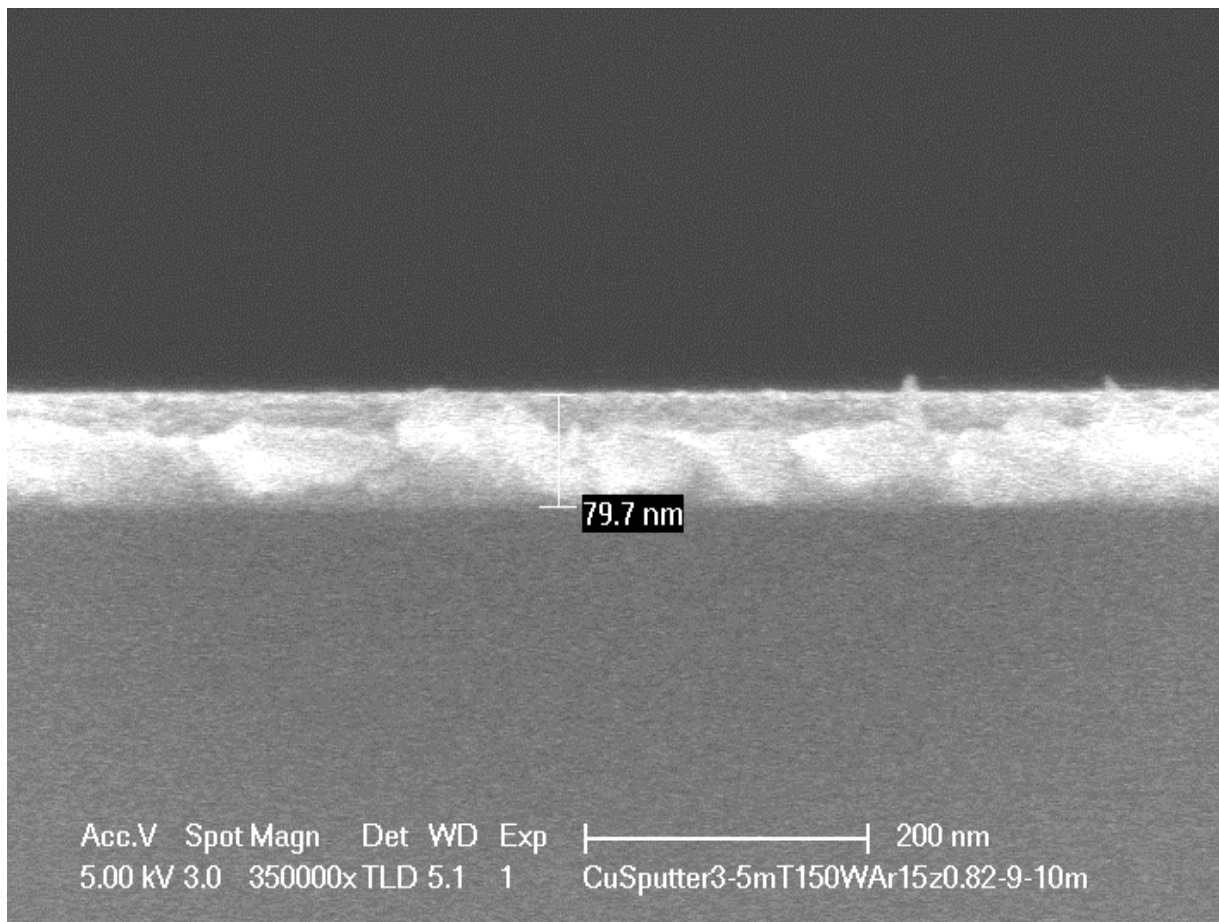


Cu Sputtering Film using Sputter#3 tool at RT									
Sample#	Pressure (mT)	DC Power (W)	Ar Flow-rate (sccm)	Time (s)	Height (inch)	Gun Angle	Rotation (rpm)	Mo Film Thickness (Å)	Sputtering Rate (Å/s)
1	5	150	15	600	0.82	9	10	798	1.330

Cu Film Stress: 249 MPa (in tensile)

Figure 1 shows the profile of Cu Film



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